

Low Skew, 1-to-11 Differential-to-3.3V LVPECL Clock Multiplier / Zero Delay Buffer

DATA SHEET

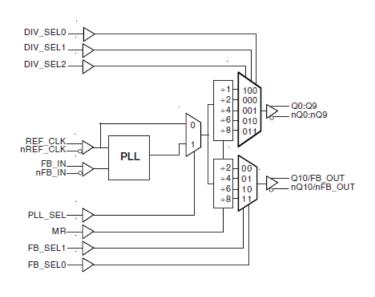
GENERAL DESCRIPTION

The 8731-01 is a low voltage, low skew, 1-to-11 Differential-to-3.3V LVPECL Clock Multiplier/Zero Delay Buffer. With output frequencies up to 700MHz the 8731-01 is targeted at high performance clock applications. Along with a fully integrated PLL the 8731-01 contains frequency configurable, differential outputs and external feedback inputs for multiplying clock frequencies and regenerating clocks with "zero delay". Frequency multiplication is achieved by utilizing the separate feedback and clock output dividers. The value of the multiplier is determined by the ratio of the feedback divider, M, to the output divider, N. For multiplier values greater than 1, M must be greater than N. For multiplier values less than 1,M must be less than N. The zero delay mode is achieved with M and N at equal values. The divide values of the clock and feedback outputs are controlled by the DIV_SEL0:2 and FB_SEL0:1 inputs, respectively. The 8731-01 accepts any differential signal and translates it to differential 3.3V LVPECL output levels.

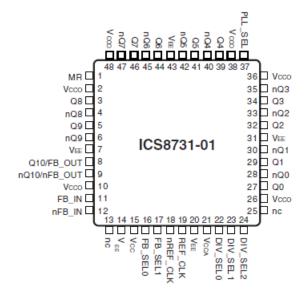
FEATURES

- Eleven differential 3.3V LVPECL outputs
- Differential reference clock input pair
- · REF_CLK, nREF_CLK pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, SSTL, HCSL
- Maximum output frequency: 700MHz
- Maximum reference clock input frequency: 200MHz
- VCO range: 250MHz 700MHz
- · Accepts any single-ended input signal with a resistor bias on nCLK input
- · External feedback for zero delay capability
- · Output skew: 70ps (maximum)
- Cycle-to-cycle jitter: 65ps (maximum)
- · Full 3.3V operating supply
- 0°C to 70°C ambient operating temperature
- Available in lead-free RoHS compliant package

BLOCK DIAGRAM



PIN ASSIGNMENT



48-Lead LQFP 7mm x 7mm x 1.4mm package body Y Package Top View



TABLE 1. PIN DESCRIPTIONS

Number	Name	Ty	/pe	Description
1	MR	Input	Pulldown	Active High Master Reset. When logic HIGH, the internal dividers are reset causing the true outputs, Qx, to go low and the inverted outputs nQx to go high. When logic LOW, the internal dividers and the outputs are enabled. LVCMOS / LVTTL interface levels.
2, 10, 26, 36, 38, 48	V _{cco}	Power		Output supply pins.
3, 4, 5, 6	Q8, nQ8, Q9, nQ9	Output		Differential output pairs.
7, 14, 20, 31, 43	V _{EE}	Power		Negative supply pins.
8, 9	Q10/FB_OUT, nQ10/nFB_OUT	Output		Differential clock outputs.
11, 12	FB_IN, nFB_IN	Input	Pulldown	Feedback input to phase detector for generating clocks with "zero delay".
15	V _{cc}	Power		Core supply pin.
16	FB_SEL0	Input	Pulldown	Determines output divider for Q10/FB outputs (see Table 3). LVCMOS / LVTTL interface levels.
17	FB_SEL1	Input	Pulldown	Determines output divider for Q10/FB outputs (see Table 3). LVCMOS / LVTTL interface levels.
18	nREF_CLK	Input	Pullup	Inverting differential clock input.
19	REF_CLK	Input	Pulldown	Non-inverting differential clock input.
21	V _{CCA}	Power		Analog supply pin.
22	DIV_SEL0,	Input	Pulldown	Determines output divider values in Table 3. LVCMOS / LVTTL interface levels.
23	DIV_SEL1	Input	Pulldown	Determines output divider values in Table 3. LVCMOS / LVTTL interface levels.
24	DIV_SEL2	Input	Pulldown	Determines output divider values in Table 3. LVCMOS / LVTTL interface levels.
13, 25	nc	Unused		No connect.
27, 28 29, 30	Q0, nQ0, Q1, nQ1	Output		Differential output pairs.
32, 33, 34, 35	Q2, nQ2, Q3, nQ3	Output		Differential output pairs.
37	PLL_SEL	Input	Pullup	Selects between the PLL and reference clock as the input to the dividers. When LOW, selects reference clock. When HIGH, selects PLL. LVCMOS / LVTTL interface levels.
39, 40, 41, 42	Q4, nQ4, Q5, nQ5	Output		Differential output pairs.
44, 45, 46, 47	Q6, nQ6, Q7, nQ7	Output		Differential output pairs.

NOTE: and refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		pF
R _{PULLUP}	Input Pullup Resistor			51		kΩ
R _{PULLDOWN}	Input Pulldown Resistor			51		kΩ



TABLE 3A. CONTROL INPUT FUNCTION TABLE FOR Q0:Q9 OUTPUTS

	Inputs						
MR	PLL_SEL	DIV_SEL2	DIV_SEL1	DIV_SEL0	Q0:Q9, nQ0:nQ9		
1	Х	Х	Х	Х	Low		
0	1	1	0	0	fVCO/1		
0	1	0	0	0	fVCO/2		
0	1	0	0	1	fVCO/4		
0	1	0	1	0	fVCO/6		
0	1	0	1	1	fVCO/8		
0	0	1	0	0	fREF_CLK/1		
0	0	0	0	0	fREF_CLK/2		
0	0	0	0	1	fREF_CLK/4		
0	0	0	1	0	fREF_CLK/6		
0	0	0	1	1	fREF_CLK/8		

TABLE 3B. CONTROL INPUT FUNCTION TABLE FOR Q10/FB

	Inputs					
MR	PLL_SEL	FB_SEL1	FB_SEL0	Q10/FB, nQ10/FB		
1	Х	Х	X	Low		
0	1	0	0	fVCO/2		
0	1	0	1	fVCO/4		
0	1	1	0	fVCO/6		
0	1	1	1	fVCO/8		
0	0	0	0	fREF_CLK/2		
0	0	0	1	fREF_CLK/4		
0	0	1	0	fREF_CLK/6		
0	0	1	1	fREF_CLK/8		

TABLE 3C. Qx OUTPUT FREQUENCY W/FB_IN = Q10/FB

Inputs						fVCO
FB IN	FB SEL1	FB SEL0	Q10/FB REF_CLK (MHz) Output Divider Mode Minimum Maximum		LK (MHz)	(NOTE 1)
FB_IN	FB_SELI	FB_SELU			Maximum	(NOTE I)
Q10/FB	0	0	÷2	125	200 (NOTE 2)	fREF_CLK x 2
Q10/FB	0	1	÷4	62.5	175	fREF_CLK x 4
Q10/FB	1	0	÷6	41.67	116.67	fREF_CLK x 6
Q10/FB	1	1	÷8	31.25	87.5	fREF_CLK x 8

NOTE 1: VCO frequency range is 250MHz to 700MHz.

NOTE 2: The maximum input frequency that the phase defector can accept is 200MHz.



ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{CC} 4.6V

Inputs, V_1 -0.5V to V_{CC} + 0.5V

Outputs, I_{\odot}

Continuous Current 50mA Surge Current 100mA

Package Thermal Impedance, θ_{JA} 47.9°C/W (0 Ifpm) Storage Temperature, T_{STG} -65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4A. Power Supply DC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, Ta = 0°C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V _{cc}	Core Supply Voltage		3.135	3.3	3.465	V
V _{CCA}	Analog Supply Voltage		3.135	3.3	3.465	V
V _{cco}	Output Supply Voltage		3.135	3.3	3.465	V
I _{EE}	Power Supply Current				195	mA
I _{CCA}	Analog Supply Current				15	mA

Table 4B. LVCMOS/LVTTL DC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, Ta = 0°C to 70°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V _{IH}	Input High Voltage	PLL_SEL, DIV_SEL0, DIV_SEL1, DIV_SEL2, FB_SEL0, FB_SEL1, MR		2		V _{cc} + 0.3	V
V _{IL}	Input Low Voltage	PLL_SEL, DIV_SEL0, DIV_SEL1, DIV_SEL2, FB_SEL0, FB_SEL1, MR		-0.3		0.8	V
I _{IH}	Input High Current	DIV_SEL0, DIV_SEL1, DIV_SEL2, MR, FB_SEL0, FB_SEL1	$V_{CC} = V_{IN} = 3.465V$			150	μА
		PLL_SEL	$V_{CC} = V_{IN} = 3.465V$			5	μΑ
I	Input Low Current	DIV_SEL0, DIV_SEL1, DIV_SEL2, MR, FB_SEL0, FB_SEL1	$V_{\rm C}C = 3.465V,$ $V_{\rm IN} = 0V$	-5			μА
'IL	·	PLL_SEL	$V_{CC} = 3.465V,$ $V_{IN} = 0V$	-150			μΑ



Table 4C. Differential DC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, Ta = 0°C to 70°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
	Input High Current	REF_CLK, FB_IN	$V_{CC} = V_{IN} = 3.465V$			150	μA
' _{IH}	Imput High Current	nREF_CLK, nFB_IN	$V_{CC} = V_{IN} = 3.465V$			5	μA
	Input Low Current	REF_CLK, FB_IN	$V_{CC} = 3.465V, V_{IN} = 0V$	-5			μA
' _L	Imput Low Current	nREF_CLK, nFB_IN	$V_{CC} = 3.465V, V_{IN} = 0V$	-150			μA
V _{PP}	Peak-to-Peak Input Voltage			0.15		1.3	V
V _{CMR}	Common Mode Inpu	ut Voltage; NOTE 1, 2		V _{EE} + 0.5		V _{cc} - 0.85	V

NOTE 1: For single ended applications, the maximum input voltage for REF_CLK, nREF_CLK and FB_IN, nFB_IN is V_+ + 0.3V.

is V $_{\rm CC}$ + 0.3V. NOTE 2: Common mode voltage is defined as V $_{\rm IH}.$

Table 4D. LVPECL DC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, Ta = 0°C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V _{OH}	Output High Voltage; NOTE 1		V _{cco} - 1.4		V _{cco} - 0.9	V
V_{OL}	Output Low Voltage; NOTE 1		V _{cco} - 2.0		V _{cco} - 1.7	V
V _{SWING}	Peak-to-Peak Output Voltage Swing		0.6		1.0	٧

NOTE 1: Outputs terminated with 50 $\!\Omega$ to V $_{\!\scriptscriptstyle CCO}$ - 2V.

Table 5. PLL Input Reference Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, Ta = 0°C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{REF}	Input Reference Frequency				200	MHz

Table 6. AC Characteristics, $V_{CC} = V_{CCA} = V_{CCO} = 3.3V \pm 5\%$, Ta = 0°C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f _{MAX}	Output Frequency				700	MHz
t _{PD}	Propagation Delay; NOTE 1	$PLL_SEL = 0V, f \le 450MHz$	4.0		5.5	ns
t(Ø)	Static Phase Offset; NOTE 2	PLL_SEL = 3.3V, DIV_SEL[2:0] = 000, FB_SEL[1:0] = 00	50		150	ps
tsk(o)	Output Skew; NOTE 3, 4				70	ps
tjit(cc)	Cycle-to-Cycle Jitter; NOTE 4				65	ps
t_	PLL Lock Time				1	ms
t_R / t_F	Output Rise/Fall Time	20% to 80%	300		700	ps
odc	Output Duty Cycle	<i>f</i> ≤ 300MHz	45		55	%

All parameters measured at f_{MAX} unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as the time difference between the input reference clock and the average feedback input signal when the PLL is locked and the input reference frequency is stable.

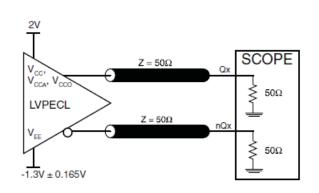
NOTE 3: Defined as skew between outputs at the same supply voltages and with equal load conditions.

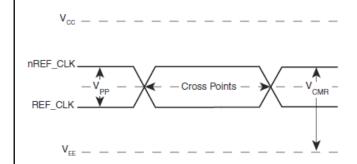
Measured at the output differential cross points.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

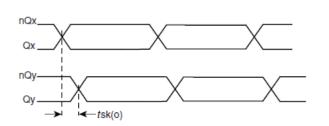


PARAMETER MEASUREMENT INFORMATION

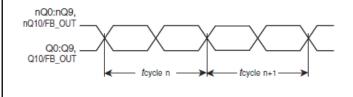




3.3V OUTPUT LOAD AC TEST CIRCUIT

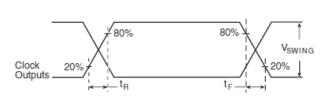


DIFFERENTIAL INPUT LEVEL

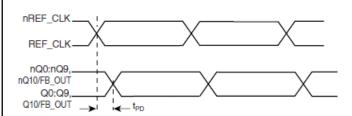


tjit(cc) = tcycle n -tcycle n+1 1000 Cycles

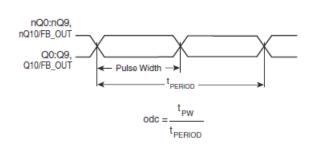
OUTPUT SKEW



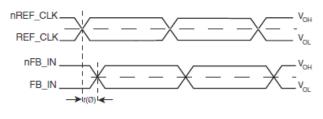
CYCLE-TO-CYCLE JITTER



OUTPUT RISE/FALL TIME



PROPAGATION DELAY



 $t(\emptyset)$ mean = Static Phase Offset

(where t(O) is any random sample, and t(O) mean is the average of the sampled cycles measured on controlled edges)

OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

STATIC PHASE OFFSET



APPLICATION INFORMATION

Power Supply Filtering Techniques

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. The 8731-01 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL. $V_{\rm CC}, V_{\rm CCA},$ and $V_{\rm CCO}$ should be individually connected to the power supply plane through vias, and bypass capacitors should be used for each pin. To achieve optimum jitter performance, power supply isolation is required. Figure 1 illustrates how a 10Ω resistor along with a $10\mu F$ and a $.01\mu F$ bypass capacitor should be connected to each $V_{\rm CCA}$ pin.

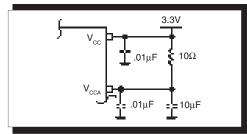
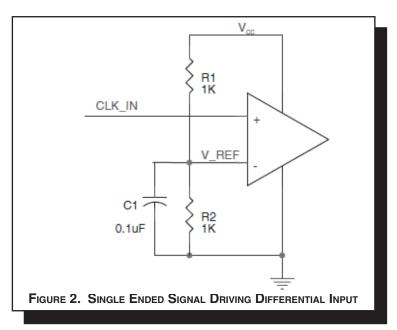


FIGURE 1. POWER SUPPLY FILTERING

WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 2 shows how the differential input can be wired to accept single ended levels. The reference voltage V_REF = $V_{\rm CC}/2$ is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the V_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and $V_{\rm CC}$ = 3.3V, V_REF should be 1.25V and R2/R1 = 0.609.





DIFFERENTIAL CLOCK INPUT INTERFACE

The REF_CLK /nREF_CLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both Vswing and Voh must meet the VPP and VcmR input requirements. Figures 3A to 3D show interface examples for the REF_CLK/nREF_CLK input driven by the most common driver types. The input interfaces suggested here are examples

only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example in *Figure 3A*, the input termination applies for LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

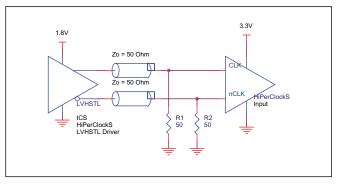


FIGURE 3A. REF_CLK/nREF_CLK INPUT
DRIVEN BY LVHSTL DRIVER

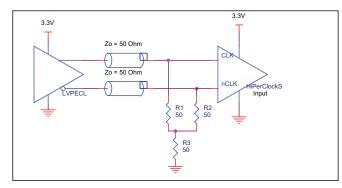


FIGURE 3B. REF_CLK/nREF_CLK INPUT
DRIVEN BY 3.3V LVPECL DRIVER

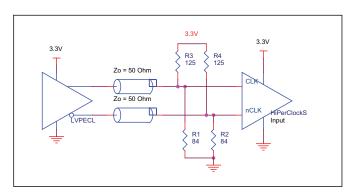


FIGURE 3C. REF_CLK/nREF_CLK INPUT
DRIVEN BY 3.3V LVPECL DRIVER

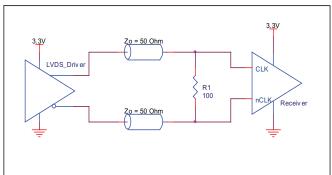


FIGURE 3D. REF_CLK/nREF_CLK INPUT
DRIVEN BY 3.3V LVDS DRIVER



RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

INPUTS:

LVCMOS CONTROL PINS:

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A $1k\Omega$ resistor can be used.

OUTPUTS:

LVPECL OUTPUT

All unused LVPECL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

TERMINATION FOR LVPECL OUTPUTS

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to

drive 50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 4A and 4B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

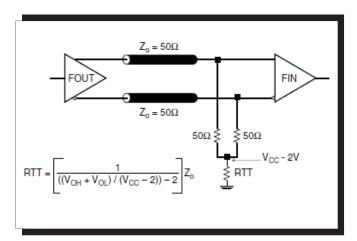


FIGURE 4A. LVPECL OUTPUT TERMINATION

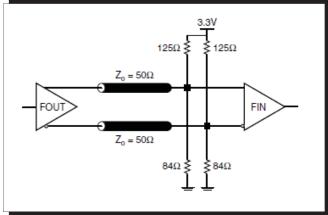


FIGURE 4B. LVPECL OUTPUT TERMINATION



SCHEMATIC EXAMPLE

Figure 5 shows an application schematic example of the 8731-01. This schematic provides examples of input and output handling. The input can accept various types of differential signal. This example shows the 8731-01 input driven by a 3.3V LVPECL driver. Additional examples for the input driven by other types of drivers are shown in the application section of

this data sheet. The 8731-01 outputs are LVPECL driver. In this example, we assume the traces are long transmission line and the receiver is high input impedance without built-in matched load. An example of 3.3V LVPECL termination is shown in this schematic. Additional termination approaches are shown in the LVPECL Termination Application Note.

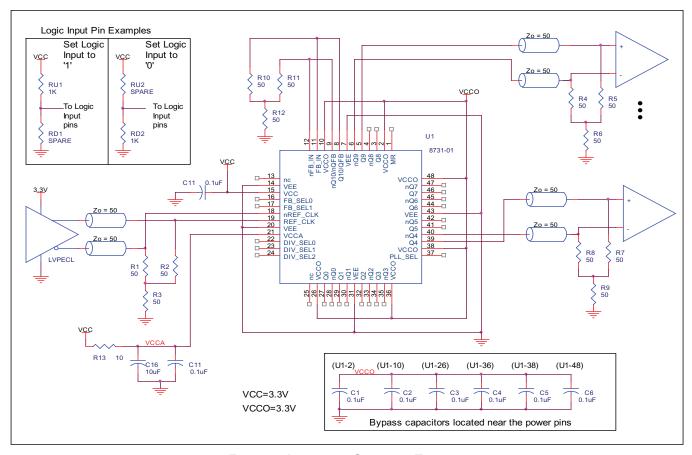


FIGURE 5. APPLICATION SCHEMATIC EXAMPLE



Power Considerations

This section provides information on power dissipation and junction temperature for the 8731-01. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the 8731-01 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for $V_{CC} = 3.3V + 5\% = 3.465V$, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)_{MAX} = $V_{CC MAX} * I_{EE MAX} = 3.465 V * 195 mA = 675.67 mW$
- Power (outputs)_{MAX} = 30mW/Loaded Output pair
 If all outputs are loaded, the total power is 11 * 30mW = 330mW

Total Power $_{\text{MAX}}$ (3.465V, with all outputs switching) = 675.67mW + 330mW = 1005.67mW

2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for the devices is 125°C.

The equation for Tj is as follows: Tj = θ_{JA} * Pd_total + TA

Tj = Junction Temperature

 θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

 $T_A = Ambient Temperature$

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ^{JA} must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 42.1°C/W per Table 7 below.

Therefore, Tj for an ambient temperature of 70°C with all outputs switching is:

 $70^{\circ}\text{C} + 1.006\text{W} * 42.1^{\circ}\text{C/W} = 112.4^{\circ}\text{C}$. This is below the limit of 125°C .

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

Table 7. Thermal Resistance θ_{JA} for 48-pin LQFP, Forced Convection

θ_{JA} by Velocity (Linear Feet per Minute)

 O
 200
 500

 Single-Layer PCB, JEDEC Standard Test Boards
 67.8°C/W
 55.9°C/W
 50.1°C/W

 Multi-Layer PCB, JEDEC Standard Test Boards
 47.9°C/W
 42.1°C/W
 39.4°C/W

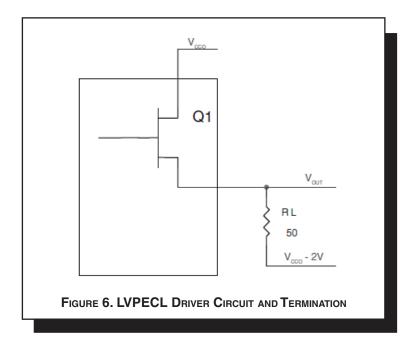
NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.



3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in Figure 6.



To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of V_{cco} - 2V.

• For logic high,
$$V_{OUT} = V_{OH_MAX} = V_{CCO_MAX} - 0.9V$$

$$(V_{CCO_MAX} - V_{OH_MAX}) = 0.9V$$

• For logic low,
$$V_{OUT} = V_{OL_MAX} = V_{CCO_MAX} - 1.7V$$

$$(V_{CCO\ MAX} - V_{OL\ MAX}) = 1.7V$$

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$$Pd_H = [(V_{OH_MAX} - (V_{CC_MAX} - 2V))/R_L] * (V_{CC_MAX} - V_{OH_MAX}) = [(2V - (V_{CC} - V_{OH_MAX}))/R_L] * (V_{CC} - V_{OH_MAX}) = [(2V - 0.9V)/50\Omega] * 0.9V = \textbf{19.8mW}$$

$$Pd_{L} = [(V_{OL_MAX} - (V_{CC_MAX} - 2V))/R_{L}] * (V_{CC_MAX} - V_{OL_MAX}) = [(2V - (V_{CC} - V_{OL_MAX}))/R_{L}] * (V_{CC} - V_{OL_MAX}) = [(2V - 1.7V)/50\Omega] * 1.7V = 10.2mW$$

Total Power Dissipation per output pair = Pd_H + Pd_L = 30mW



RELIABILITY INFORMATION

Table 8. $\theta_{\text{JA}} \text{vs. Air Flow Table for 48 Lead LQFP}$

θJA by Velocity (Linear Feet per Minute)

	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for 8731-01 is: 2883



PACKAGE OUTLINE - Y SUFFIX FOR 48 LEAD LQFP

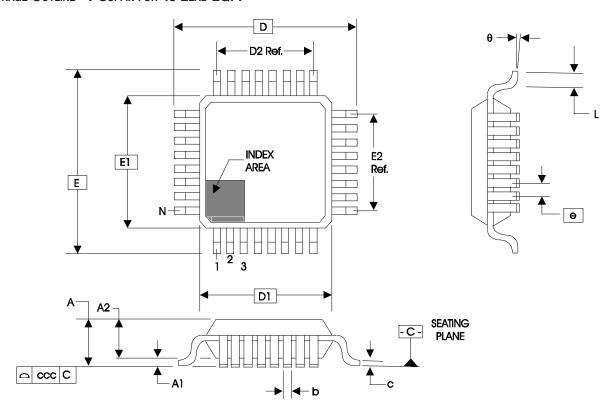


TABLE 9. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS							
SYMBOL	BBC						
	MINIMUM	NOMINAL	MAXIMUM				
N	48						
Α			1.60				
A1	0.05		0.15				
A2	1.35	1.40	1.45				
b	0.17	0.22	0.27				
С	0.09		0.20				
D		9.00 BASIC					
D1		7.00 BASIC					
D2		5.50 Ref.					
E		9.00 BASIC					
E1		7.00 BASIC					
E2		5.50 Ref.					
е		0.50 BASIC					
L	0.45	0.60	0.75				
θ	0°		7°				
ccc			0.08				

Reference Document: JEDEC Publication 95, MS-026



Table 10. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
8731CY-01LF	ICS8731CY01L	48 Lead "Lead-Free" LQFP	tray	0°C to 70°C
8731CY-01LFT	ICS8731CY01L	48 Lead "Lead-Free" LQFP	tape & reel	0°C to 70°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.



	REVISION HISTORY SHEET					
Rev	Table	Page	Description of Change			
А	T10	1 15	Features Section - added Lead-Free bullet . Ordering Information Table - added Lead-Free part number, marking and note.	6/6/06		
В	T10	15 17	Updated datasheet's header/footer with IDT from ICS. Removed ICS prefix from Part/Order Number column. Added Contact Page.	7/27/10		
В	T10	15	Ordering Information - removed leaded devices. Updated data sheet format.	7/14/15		



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